



**FEATURES**

- TO-8 hermetic package
- Optimized die size for maximum signal
- Low capacitance



**ELECTRO-OPTICAL CHARACTERISTICS AT 25°C**

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Active Area	9.91mm x 4.28mm		42		mm <sup>2</sup>
Responsivity, $\mathcal{R}$	@ 450nm	0.20	0.28		A/W
Dark Current, I <sub>dr</sub>	V <sub>R</sub> = 10V		11	25	nA
Reverse Breakdown Voltage, V <sub>R</sub>	I <sub>R</sub> = 10A	25	60		Volts
Capacitance, C	V <sub>R</sub> = 10V		85		pF
Rise Time	V <sub>R</sub> = 10V		30		nsec
Series Resistance	V <sub>f</sub> = 1V		35	100	Ohms

**THERMAL PARAMETERS**

Storage and Operating Temperature Range	-55°C TO 100°C
Maximum Junction Temperature	100°C
Lead Soldering Temperature <sup>1</sup>	260°

<sup>1</sup> 1/16" from case for 10 seconds.

